How EDA Could Save the World (of Computing)

Todd Austin University of Michigan



Perspectives on Scaling

C-FAR: Center for Future Architectures Research

- Focused on scaling in 2020-2030 silicon
- Performance, power and cost
- 27 faculty at 14 universities, 92 students

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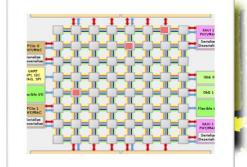
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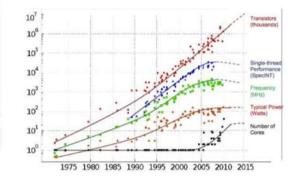
All of the work presented in this talk is that of *C-FAR faculty*.

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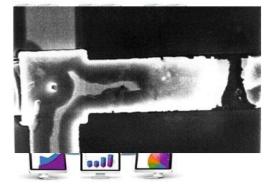
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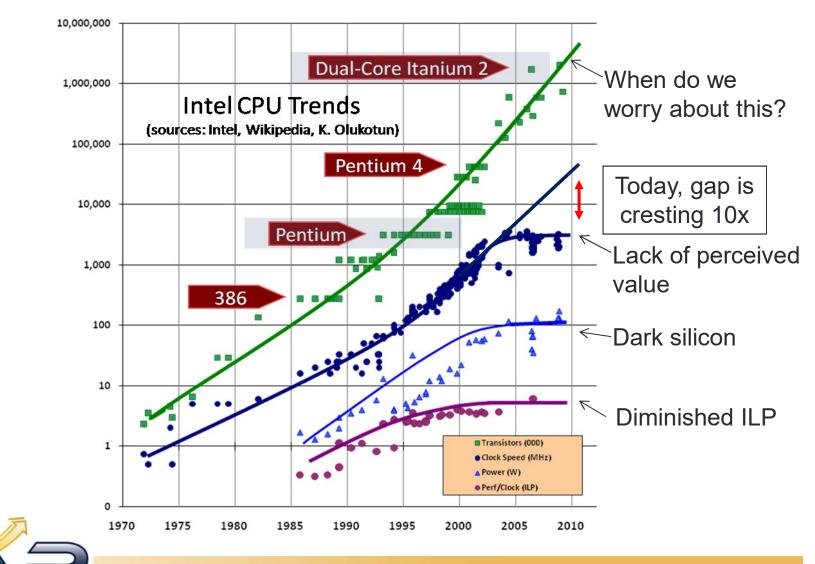


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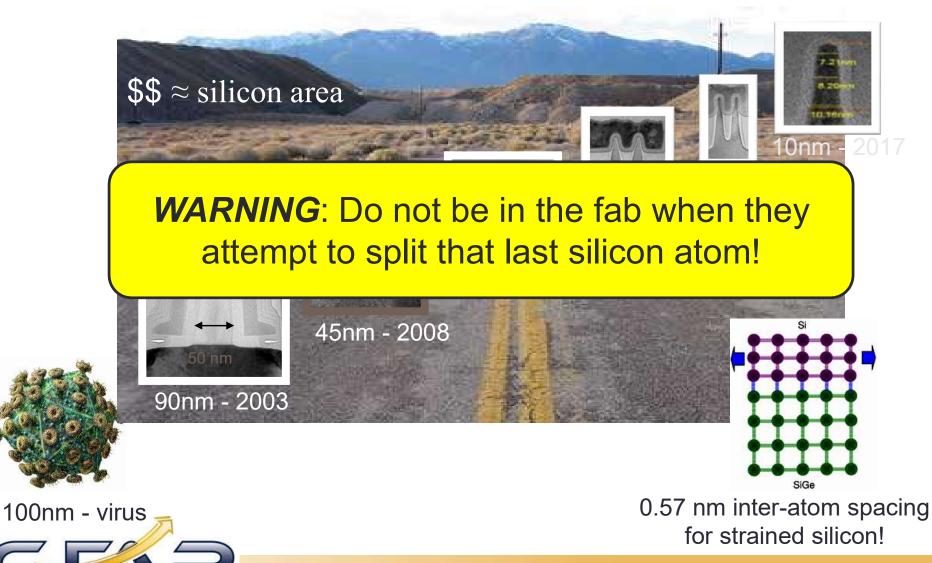




Moore's Law Performance Gap



Moore's Law vs. Physics

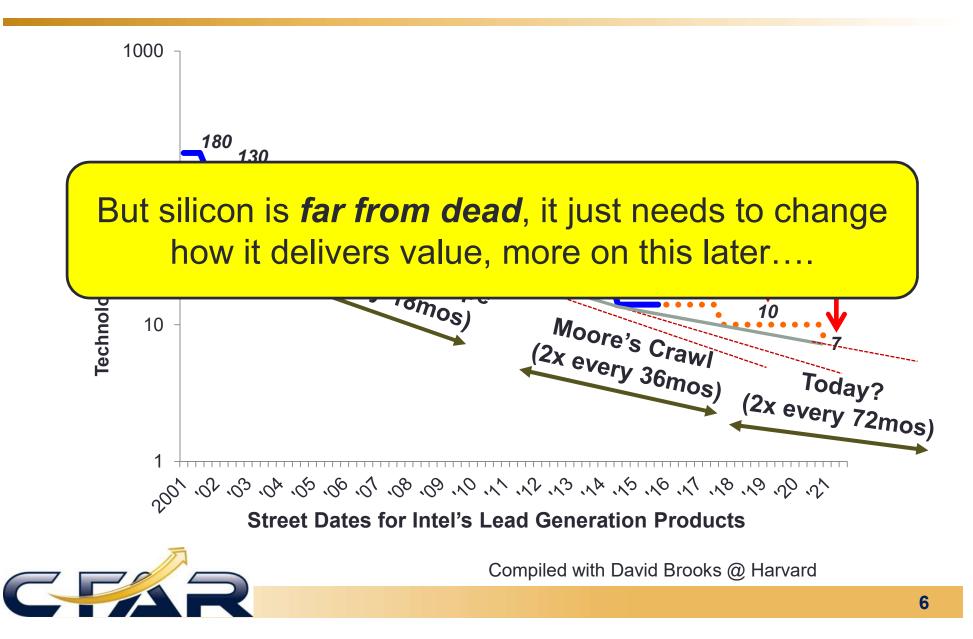


Moore's Law vs. Economics



Sources: Intel Investor Meeting 2014, GlobalFoundries, Intel, TSMC

The Inevitable Becomes Real



What Does This Mean to System Designers?

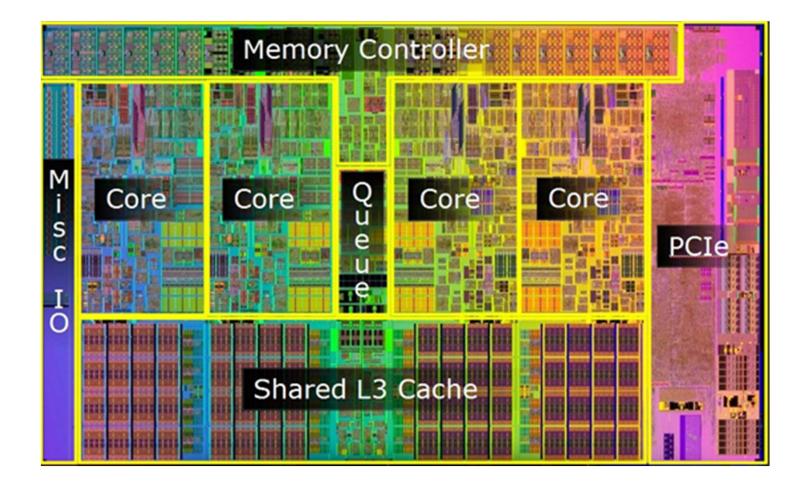
Today, value = scalability (performance, power, cost).

But, the *Dennard scaling* has left us, and *silicon dimensional scaling* scaling is slowing.



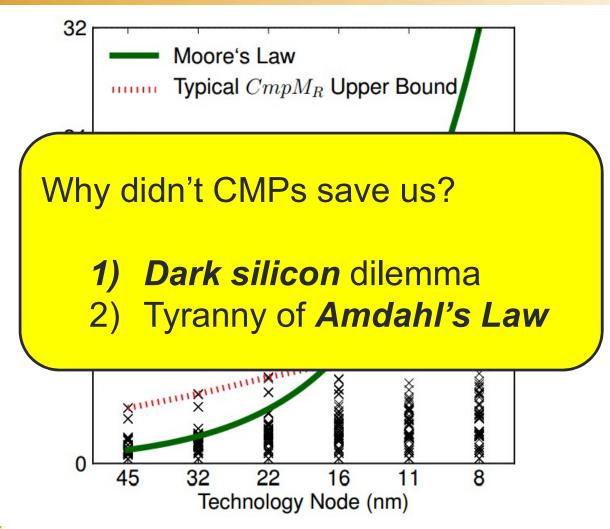


Remedy #1: Chip Multiprocessors





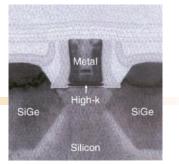
CMP Performance Scaling for the Highly Parallel PARSEC Benchmarks

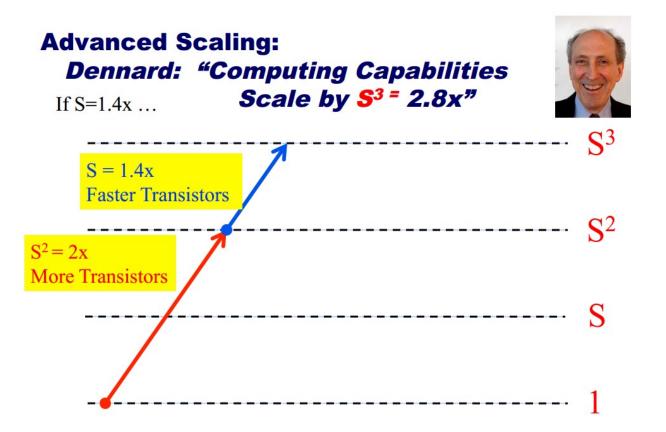


From "Dark Silicon and the End of Multicore Scaling," by Esmaeilzadeh et al.



The Dark Silicon Dilemma



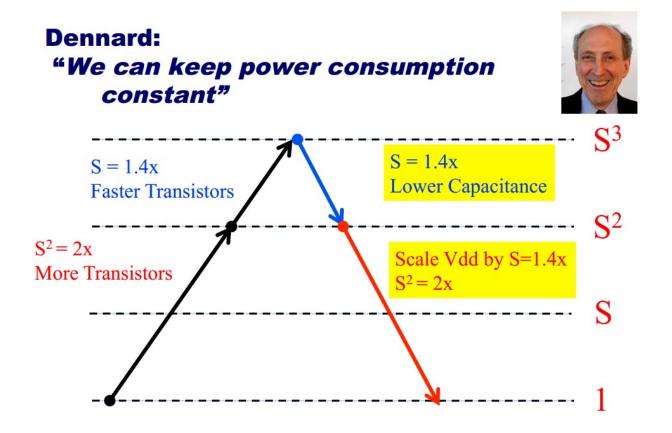




Courtesy Michael Taylor @ UWash

The Dark Silicon Dilemma

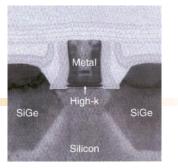
Metal High-k SiGe SiGe Silicon



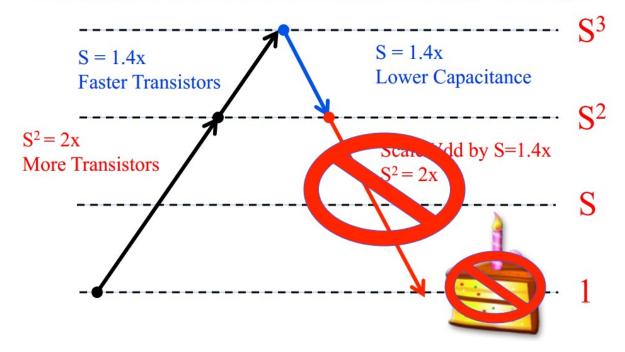


Courtesy Michael Taylor @ UWash

The Dark Silicon Dilemma



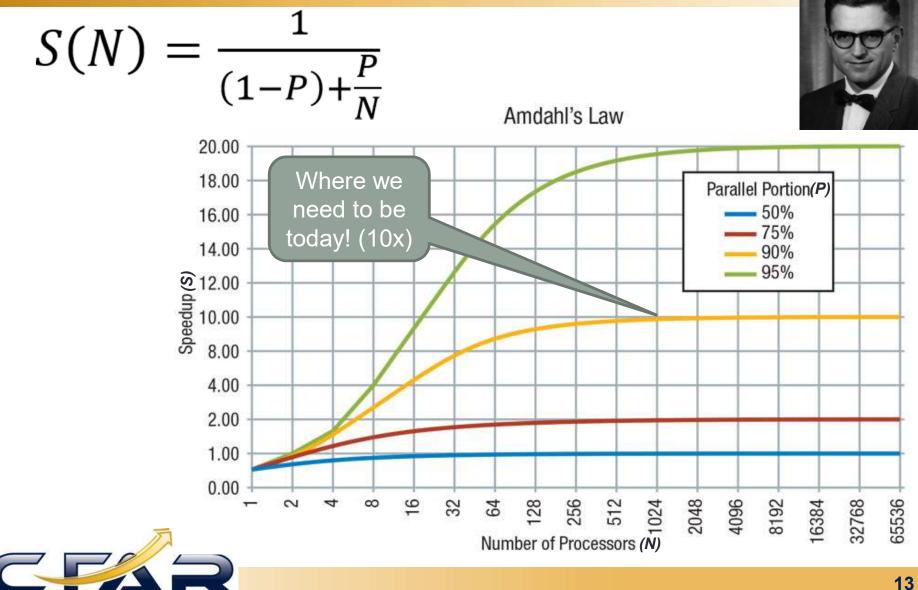
Fast forward to 2005: Threshold Scaling Problems due to Leakage Prevents Us From Scaling Voltage





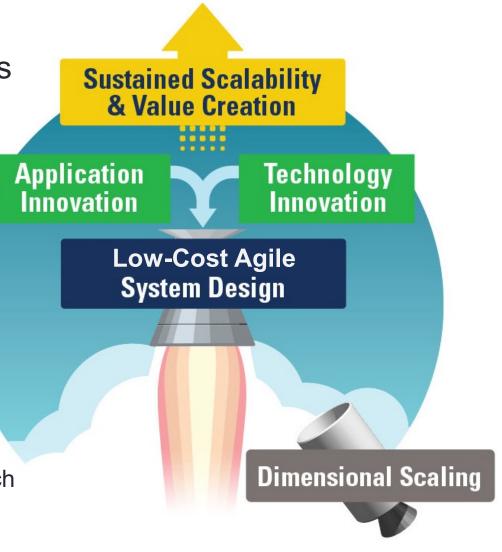
Courtesy Michael Taylor @ UWash

The Tyranny of Amdahl's Law



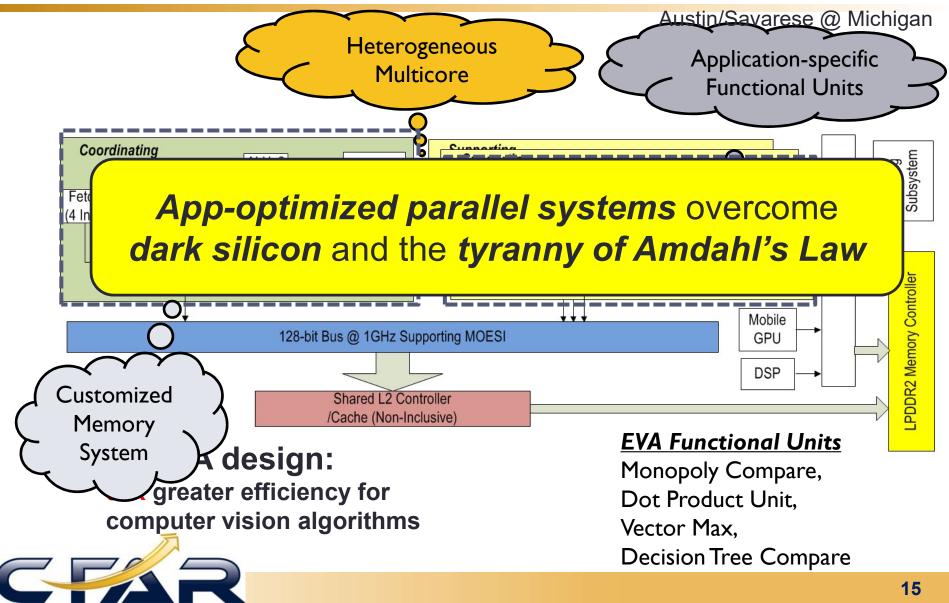
Where Should We Go Next?

- Value creation requires sustained innovation sources
 - Traditionally dimensional scaling
- New source: applications
 - Rely on fast-changing app space to deliver perf/power/cost value
- New source: silicon tech
 - Rely on structure, materials, and device advances in silicon
- Both sources necessitate low-cost agile design
 - Cheaply translate apps to systems
 - Effectively connect apps to new tech





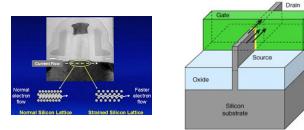
Application Innovation: EVA Embedded Vision Architecture

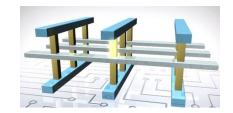


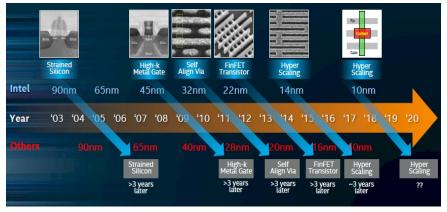
Technology Innovation: Beyond dimensional scaling

- For quite some time, silicon advances have been supported by technology advances
 - Strained silicon, High-k materials, FinFETs
- More coming, and the pace of this innovation will likely increase
 - Intel/Micron's XPoint memory technology
 - Intel's "hyperscaling" technologies
- Many additional opportunities possible
 - TFETs, CNTs, spintronics, novel materials, analog accelerators, etc...
- Key question: will silicon scaling cost advantages persist?
- Key challenge: driving tech advances for maximum system impact









Why These Ideas Will Likely Fail, Unless We Make a Change...

- The Good: App/tech optimized systems can close the Moore's Law gap
- The Bad: Dennard scaling has stopped, Moore's Law is slowing, leaving a growing scalability gap
- The Ugly: The app/tech optimized designs needed to close the gap will be too expensive to afford

• We must work to make design much *cheaper*!



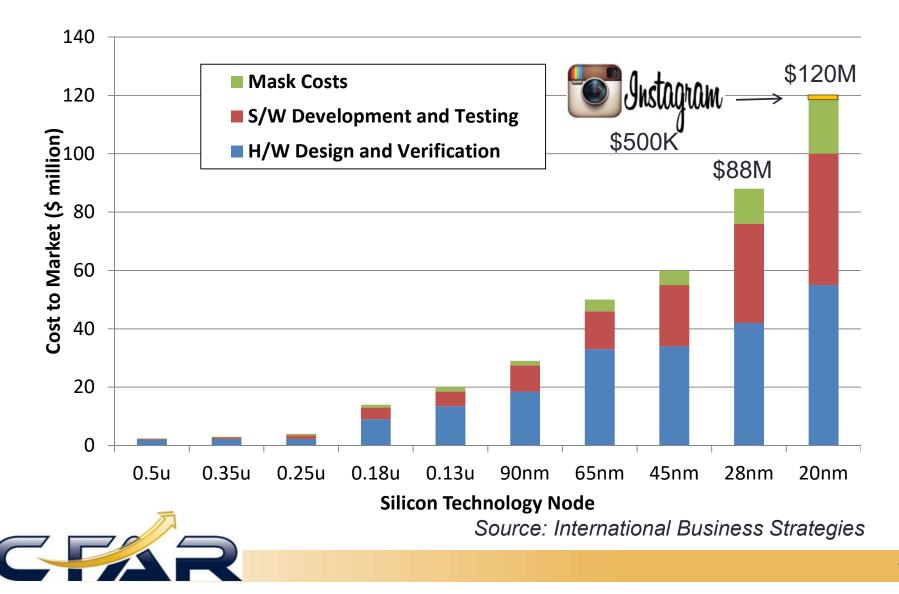


What I Want You to Remember

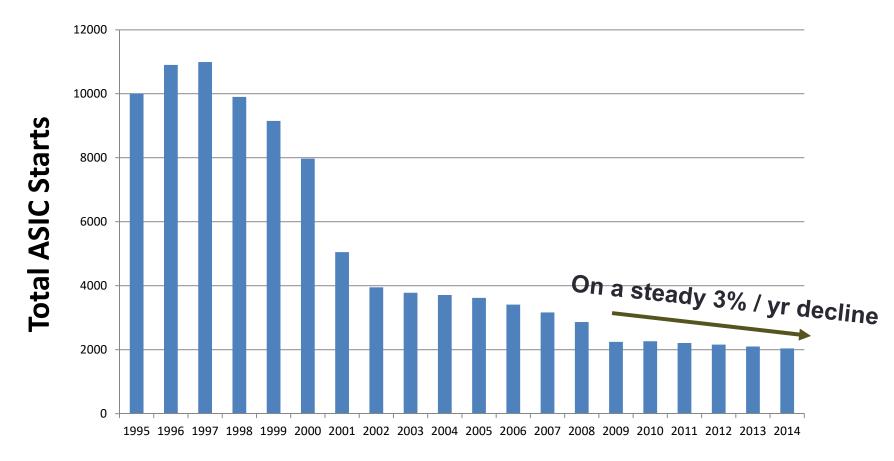
- Successfully bridging the Moore's Law performance gap is less about "*How*" to do it and more about "*How Much*" does it cost!
- My claim: if we can effect a 100x reduction in the cost to bring a design to market, innovation will flourish and scaling challenges will be overcome.



Design Costs Are Skyrocketing



Outcome: "Nanodiversity" is Dwindling



Year



Source: Gartner Group

The Remedy: Scale Innovation

- Ultimate goal: accelerate system innovation and make it sufficiently inexpensive that anyone can do it anywhere
 - \$1M for idea-to-market
 - Requires a 100x decrease in design costs
- Things you cannot do (and still meet the \$1M design point):
 - Design new accelerators
 - Specify the design in low-level RTL
 - Write low-level software
 - Verify everything
 - Fabricate a chip (in full production)
 - License today's expensive 3rd part IP



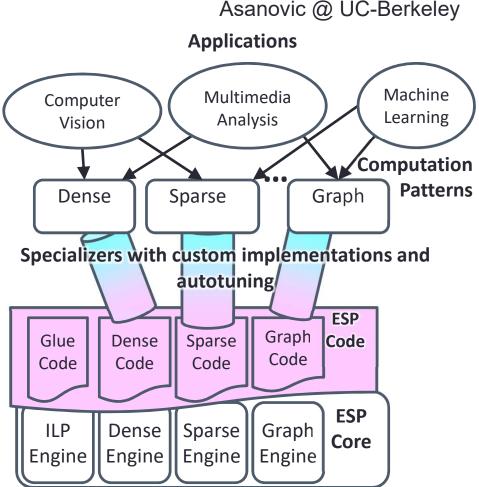
The Remedy: Scale Innovation

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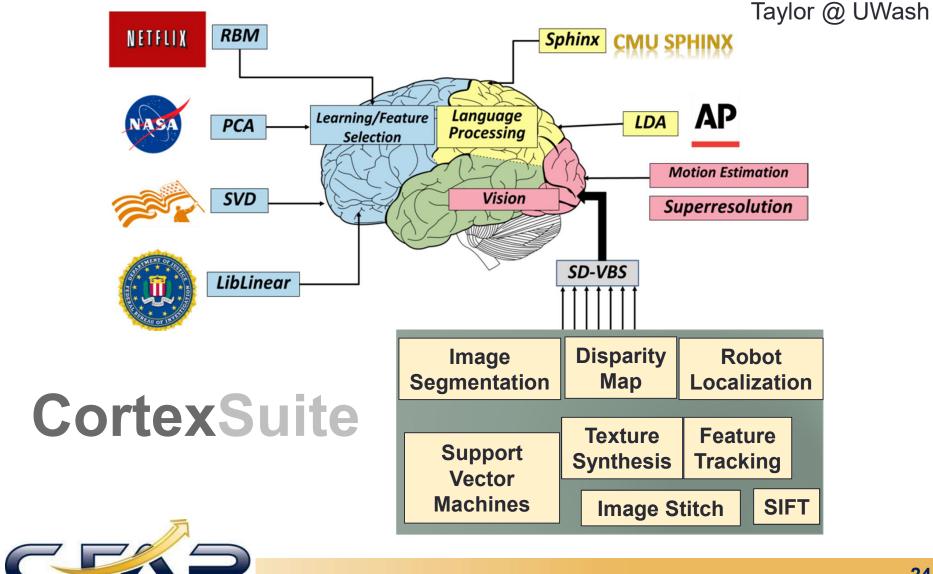
1) Embrace system-level design with reusable algorithm-inspired components

- System-level design delivers higher efficiency and productivity
- Example: Ensembles of Specialized Processors (ESP)
- Reusability achieved by targeting algorithms rather than apps
 - All apps built on a few dozen algs
 - Dense linear algebra vs. GPU
- Grand challenges remain: what are the components and how are they connected?





Application-Driven Design Requires Expertise with Emerging Applications



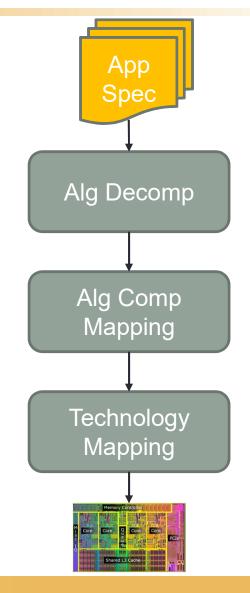
The Remedy: Scale Innovation

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- Remedy #2: Evolve EDA into language-to-package correct-byconstruction design flows



2) Evolve EDA into language-to-package correct-by-construction design flows

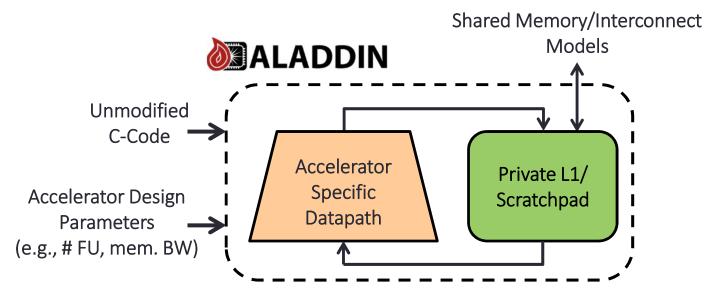
- Today, EDA focuses on RTL-totechnology mapping
- Tomorrow, EDA must evolve to app-to-technology mapping
 - DSL or language level app spec, to...
 - Decomposed app, matching reusable algorithmic components, to...
 - Programmed and balanced algorithmic components with appropriate interfaces, to...
 - Technology-mapped application
- Would greatly boost productivity
- Tool verification would ensure much of the design is correct-by-construction





Aladdin Pre-RTL Analysis Tool

Brooks @ Harvard



- · Aladdin high-level synthesis tool
 - Analyzes *language-level specification* of accelerator under designer constraints
 - Utilizes design space exploration to efficiently identify performance, power, and area optimized designs
 - Considers both computational and memory components



The Remedy: Scale Innovation

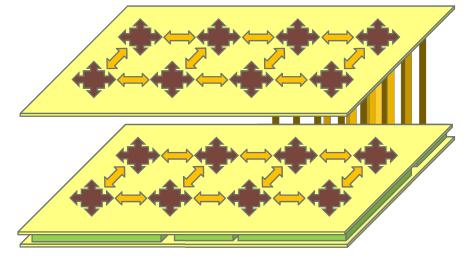
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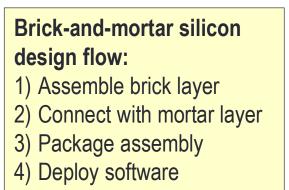


3) Mature system-in-package technologies to enable package-time custom ICs with low NRE costs

Bertacco/Das @ Michigan

 System-in-package technologies enable assembly-time customization, i.e., MCMs + 3D + reconfigurable interconnect





- Customized design made from physical alg components
- Component NRE costs amortized across all designs
- Key hurdle: placement and connection tolerant integration



The Remedy: Scale Innovation

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- Remedy #4: Let system demands drive silicon technology advances



4) Let system demands drive silicon technology advances

- Reduced leakage for computation/memory
- More efficient communication w/o more latency
- More efficient computation that is dense and cheap
- Could silicon advances have bigger impacts?
- Controllable and recognizable analog functions
 - Allows computation to be replaced with fast and efficient analog compute
- Emerging tech that delivers value at low fault rates
 - Many low-cost fault tolerance techs exist today, limit faults to < 0.1%
- Fast, efficient, non-destructive writes for NVM
 - Gives simpler, denser, more efficient mem, enables ultra-low power
- Computation w/o power/electrical signature
 - · Systems are riddled with side channels, needed to establish H/W trust



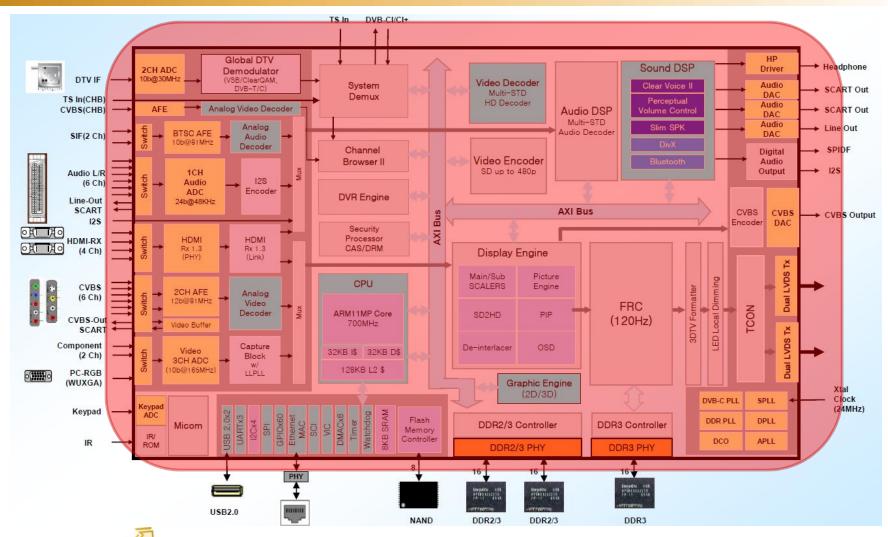


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- Remedy #5: Embrace open-source H/W to focus industry investment



5) Embrace open-source H/W to focus industry investment



CFAR

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Red = non-free IP, Green = free IP

5) Embrace open-source H/W to focus industry investment





Red = non-free IP, **Green** = free IP

Does Open-Source H/W Mean an End to Profits?

- No, not in the way I am suggesting we utilize open source...
- We need to decide as a community what IP is no longer worth investing in its closed-source development

Open source helps to ensure that every \$ invested creates *customer-perceived value*.

investment on developing new closed-source IP

 Over time the availability of open-source IP grows, and the cost of bringing new IP to the market is further mitigated

• Consider: How did Instagram come to market for \$500k?



Good News: Open-Source H/W is Growing





OpenPiton





Conclusions

- App and technology optimized design could continue Moore's Law scaling benefits
 - But, it requires a diverse hardware ecosystem with affordable customization
- Effective and affordable customization won't happen without our help
 - 1. Embrace system-level innovation w/ reusable parts
 - 2. Evolve EDA into language-to-package flows
 - 3. Mature system-in-package technologies
 - 4. Let system demands drive silicon technology
 - 5. Embrace open-source H/W
- Increasing "nanodiversity" is a good thing
 - More jobs, companies, and students
 - More competition and scalable innovation







Questions

